

EPTC 2008

10th Electronics Packaging Technology Conference
9th - 12th December 2008 @ Grand Copthorne Waterfront Hotel, Singapore

EPTC 2008 is a 4-day event in conjunction with our 10th-year anniversary celebration. The EPTC Technical Committee with over 100 technical experts has reviewed a total of 351 abstracts from 30 countries submitted for the conference. 260 quality papers from engineers and researchers have been selected for presentation in 48 technical sessions. These papers cover a wide spectrum of topics, including electronic components, materials, assembly, packaging, system packaging, optoelectronics, quality & reliability, modeling & simulation, and emerging technology topics.

We are privileged to have 3 distinguished **keynote speakers**, Dr. GQ Zhang of NXP Semiconductor, Prof. Michael Pecht of the University of Maryland, and Prof. CP Wong of Georgia Tech, to deliver keynote talks. We are also glad to invite 6 pioneers from 6 regions to share their reviews in the plenary session: "**3D System Integration - Where Is It Heading? US, Europe or Asia?**". This year, 18 invited paper talks will be given during the technical sessions by experts from various fields of packaging technologies, so that attendees will have much deeper insight into the latest research challenges in packaging.

The EPTC also features **professional short courses** and forums, covering 8 different topics offered by world-class experts in their fields. A tabletop **exhibition** featuring suppliers of materials, equipment, components, software and service providers for the microelectronics and electronic assembly industries will be held during EPTC. Last but not least, we have specially arranged a memorable **10th anniversary EPTC banquet** at the Singapore Turf Club, an excellent social event for professional networking.

Register online at www.eptc-ieee.net

You may download the **Advance Program**:

eptc.elite.sg/2008/download/EPTC%202008%20Advance%20Program.pdf

We are looking forward to seeing you at EPTC in Singapore!

Best regards

Dr. Tong Yan TEE

General Chair, EPTC 2008

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Dr. Teck Kheng LEE

Technical Chair, EPTC 2008

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IEEE COMPONENTS, PACKAGING AND
MANUFACTURING TECHNOLOGY SOCIETY

SYMPOSIUM on

Design, Test, Integration & Packaging of MEMS/MOEMS

This series of Symposia is a unique single-meeting event expressly planned to bring together participants interested in manufacturing microstructures and participants interested in design tools to facilitate the conception of these microstructures. Again, a special emphasis will be put on the very crucial needs of MEMS/MOEMS in terms of packaging solutions. The goal of the Symposium is to provide a forum for in-depth investigations and interdisciplinary discussions involving design, modeling, testing, micromachining, microfabrication, integration and packaging of structures, devices and systems.

DTIP

of MEMS & MOEMS

Abstracts are requested, by **November 10, 2008**

For further information, visit our website:

cmp.imag.fr/conferences/dtip/dtip2009



Alternating with the IEEE ESTC, EMPC is a Europe's premier conference planned every two years in a different European country, bringing together specialists from industry and academia. EMPC addresses "everything in electronics between the chip and the system".

The Technical Program Committee of EMPC 2009 **invites you to send abstracts** of original work describing recent developments in microelectronics technologies:

ADVANCED PACKAGING:

- Single Chip and Multi Chip Packaging, Wafer Level Packaging, 3D-WLP, 3D-IC, SIP, SOP and other System Integration Technologies
- Embedded Passives on Wafers and Substrates
- High Frequency and High Power Packaging;
- LTCC Ceramics Technologies
- PCB and BGA Substrates Design and Technologies, Laminates, Micro-Vias and Build-Up Technologies, Flex

INTERCONNECTION TECHNOLOGIES:

- Thick and Thin Film Technologies
- Wire Bonding, Bumping, Flip Chip Bonding
- Cu/Low-k Wafers, Through Silicon Vias
- Lead-Free Soldering and Adhesive Joining

POWER ELECTRONICS:

- Application in Consumer, Telecom, Automotive, Wearable, Space and Defense

MORE THAN MOORE:

- MEMS Packaging: MEMS Based Sensors and Actuators Packaging, RF-MEMS, Optical MEMS, Bio-MEMS
- Optoelectronics: Power LED Packaging and Light Guiding, Packaging of Optoelectronic Modules suitable for Gb/s Fiber Optic Communication
- Solar Energy (Photovoltaics): Packaging Design to improve Efficiency of Photovoltaic modules Reliability and Qualification Approaches
- Nano Technologies: Smart Materials, Interconnections, Nano-Scale Packaging
- Medical Electronics: Applications, Design, Development, Manufacturing that comply with complex and demanding regulations and market requirements.

MANUFACTURING TECHNOLOGIES AND MATERIALS:

- Process Development, New Equipment, Yield Improvement, Cost and Cycle Time Reduction, Green Mfgng
- Adhesives, Encapsulants, Underfills, Moulding Compounds, Lead-Free Solder Alloys, Halogen Free Materials, Dielectrics and Ceramics.

Abstracts due: **December 31, 2008**

More information:

www.empc2009.org

2009 European Systems Packaging Workshop

February 2-4, 2009 Kinsale, Ireland

Systems Packaging deals with optimizing all aspects of technology at the product level. It encompasses architecture, electrical design, thermal management, all levels of packaging and cost from a holistic perspective. As a result, Workshop attendees will get an overview and insight into all aspects of the electronics industry. The CPMT Society's **TC on Systems Packaging** began in 1968 and its members possess a great amount of industry experience that newcomers can tap into. Workshops are informal, with many opportunities to network with and learn from your peers. The 2009 workshop topics are:

Smart Systems
Communications Systems
High Performance Computing

Biomedical Systems
Photonics

If you want to see leading edge work in electronics, this is the meeting to attend. More information can be found at the following website:

www.ewh.ieee.org/soc/cpmt/tc14/

*This workshop will be the 11th one held in Europe by the TC on Systems Packaging.
We hope to see you in Kinsale (County Cork), Ireland next February.*

The 2009 IEEE International Workshop on Portable Information Devices

September 20 – 22, 2009, Anchorage, Alaska, USA



CALL FOR ABSTRACTS/PARTICIPATION

The **Portable 2009 Conference** will be co-located with the 70th IEEE Vehicular Technology Conference at the Anchorage Hilton, AK, USA, from September 20 – 22, 2009. Portable 2009 will bring together electrical, materials, mechanical, optical, reliability, industrial and manufacturing engineers, as well as business leaders involved or interested in various types of Portable Information Devices (PIDs), to address and discuss the state-of-the-art, challenges, attributes and pitfalls in PIDs and related areas.

We are looking for **technical paper contributions** (initially, in the form of **extended abstracts**, and then in the form of full-length papers), coupled with **tutorial, panel discussions, and demonstration** (trade show type) proposals on various aspects of PID engineering, including, but not limited to:

- Functional (electrical, optical) and Physical Design, Packaging, Physics, Mechanics, Materials, Manufacturing and Reliability of PIDs, Cellular Phones and other Mobil/Wearable Devices;
- Hardware/Software Interaction and Power Generation, Supply and Conversion;
- Special Areas of Applications (e.g., Bio-Medical) and Use of Nano-technologies;
- Multi-Modal Man-Machine Communication; Anywhere/Anytime Access to Information and Audio and Video Recognition and Processing;
- Predictive Modeling and Experimental Evaluations and Testing;
- Economics, Business, Government/Regulatory and Homeland Security Related Issues;
- Home Entertainment Systems and Networks, and other Social Areas, and Impact on society.

Submit abstracts to William Yeager, Sun Microsystems: yeager_william@earthlink.net

PORTABLE 2009 Website: www.ieeevtc.org/portable2009

FIRST CALL FOR PAPERS: SPI'09

The 13th IEEE Workshop on

SIGNAL PROPAGATION ON INTERCONNECTS

Hotel Sofitel, Strasbourg, France

May 12-15, 2009

During the last twelve years, the **IEEE Workshop on Signal Propagation on Interconnects** has developed into a forum of exchange on the latest research and developments in the field of interconnect modeling, simulation and measurement at the chip, board, and package level. The event is also meant to bring together developers and researchers from industry and academia in order to encourage cooperation. In view of the last years' successes, the committee is looking forward to the 13th SPI where world class developers and researchers will share and discuss leading-edge results. The workshop will be held in English.

Submission of abstracts:

Those who wish to contribute to the workshop should send (by e-mail only) a formatted two-page to four-page paper to the Program Chair by **February 7, 2009** (please see the submission instructions on our website).

If the paper is accepted, it will be reproduced, as is, in the workshop proceedings.

Notification about acceptance will be given by March 16, 2009.

Detailed information about the workshop and its location are available on the website:

spi.univ-brest.fr

The committee is looking forward to your participation.

Call for Papers:

**Thermal, Mechanical and Multiphysics
Simulation and Experiments
in Micro-Electronics and Micro-Systems**

EuroSimE

Delft, The Netherlands April 26-29, 2009

The conference addresses the results of both fundamental research and industrial application for thermal, mechanical and multiphysics solutions of (micro)-electronics and microsystems, focusing on advanced simulation and experiments. You are invited to submit an abstract in any of the following areas:

- Mechanical simulation (static & dynamic)
- Thermal simulation (steady state & transient)
- Failure analysis and failure mode extraction
- Material characterisation, experiments and modelling
- Validation of simulations by experiments
- Failure criteria and damage-modelling
- Behavioural modelling
- Compact modeling and model order reduction

Back to its roots! EuroSimE 2009 will be celebrating its tenth anniversary, as it was born in March 2000 in the Netherlands. Join us for this great and unforgettable event!

- Short courses for professional training.
- Three days of technical sessions for oral and poster presentation.
- A parallel exhibition from hardware, simulation and optimization software companies.

Applications:

- Components and packaging
- Opto-electronic packages
- High temperature packaging
- Piezoelectric components
- Packaging for harsh environments
- Wafer processing, chip design and reliability
- Nanoelectronics
- PWB design and application
- Electronics system assembly
- Photovoltaics

Upload your abstract on our website:

www.eurosime.org

Abstracts must be received by **November 15, 2008**

2009 European Systems Packaging Workshop

February 2 – 4, 2009

Kinsale (County Cork), Ireland

The IEEE Technical Committee on Systems Packaging (TC-SP) wishes to invite you to its 11th European Workshop. Our goal is to view all types of packaged electronics from the macro perspective with emphasis on the overall technical system attributes, choices and challenges. This includes the product specifications, system architecture, technologies, electrical performance, power design and thermal management. We approach the product characteristics by focusing on all levels of packaging as the "glue" that holds the entire hardware system together. Consequently, designing the total package requires an intimate knowledge of all the technologies that go into the final product. This perspective leads to a broad knowledge of what's going on in all aspects of the worldwide electronics industry. So if you can't go to all the sub-specialty conferences and you want an in-depth big picture view of the latest developments in the field of electronics, you should seriously consider attending this workshop.

The workshop will be conducted in English. It will be held at the Trident Hotel. Program, hotel and registration information can be found at this website as it becomes available. The committee is looking forward to your participation.

Session Topics are:

- + Smart Systems
- + Biomedical Systems
- + Communications Systems
- + Photonics
- + High Performance Computing

For more information, visit the website:

[www.ewh.ieee.org/soc/cpmt/tc14/
Cork09/ESPW09.html](http://www.ewh.ieee.org/soc/cpmt/tc14/Cork09/ESPW09.html)



EDAPS 2008 Symposium

IEEE

Electrical Design of Advanced Packaging and Systems

December 10 (Wednesday) ~ 12 (Friday), 2008
COEX Convention Center, in downtown at Seoul, Korea

December 10-12, 2008 Seoul, Korea

The EDAPS Symposium is to enhance the technical awareness and depth in the Asia region specifically in area of package and system electrical design concepts, issues, and challenges ahead for next generation electronic products.

- * Specially selected technical papers
- * Single session in a single room.
- * Oral presentation (about 30 papers)
- ... * poster session (about 30 papers)
- * Plenary talks from leading industry and academia
- * Tutorials
- * Exhibition
- * Student Paper Award

Topics

- * High-speed Digital Signal Integrity Modeling, Design
- * Power Distribution Network Modeling, Measurement
- * SiP/SoP Design
- * High-performance Packaging for SoC
- * RF/Microwave Packaging for Wireless Communication
- * Interconnect Modeling, Simulation, and Measurement
- * Embedded Passives Modeling and Measurement
- * High-speed Channels Modeling and Measurement
- * EMI/EMC Modeling and Measurement
- * EDA tools for chip, package, and board co-design

Download the Advance Program:

www.edaps2008.org

Contact: S.M Yang, yangsm@ee.kaist.ac.kr
(Office: 82-42-869-5458)



Printed Electronics USA08

December 2-5, 2008
San Jose Convention Center
San Jose, CA USA

**The world's largest and
most comprehensive event
on the new electronics**

The **fifth annual Printed Electronics USA** conference and exhibition covers all the applications, technologies and opportunities. Anticipating over 800 delegates and 80 exhibitors, this is the World's largest event on the topic.

Printed Electronics USA gives the big picture, not least by inviting leading speakers from across the world. Commercialization and the full range of technologies are the emphasis, with inorganic solutions receiving equal emphasis with organic and hybrid solutions – thus reflecting the situation in the real world.

A full range of devices, materials and production technologies will be explained by best-in-class speakers, with many first announcements. Samples and demonstrations will be available and many subjects will be aired for the first time.

There will be sessions on the latest breakthroughs in electronics on paper and on many new types beyond silicon, such as smart skin patches and photovoltaics.

Over 100 world class speakers - some presenting exclusively for the first time here - cover components, materials and applications in the following sessions:

- Analyst forecasts and trends
- Healthcare and bionic man
- Radical new printed electronic products
- Improving traditional electronics
- New possibilities with printed electronics
- Flexible lighting and its applications
- Thin film photovoltaics and batteries
- Sensors
- Smart substrates/stretchable electronics
- Materials
- Manufacture

The Exhibition (Dec 3-4)

Covering the world of organic and printed inorganic solutions: Companies exhibiting cover materials, manufacture, device production, consulting, academic research and more. 80 anticipated exhibitors will make this the largest exhibition on Printed Electronics in the world.

Save through November 14th. For more information, visit

www.IDTechEx.com/peUSA

IEEE Components, Packaging and Manufacturing Technology Society

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Visit our website
www.cpmt.org

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